

Atty. Docket No. CPAC 101-2
Appl. No. 10/084,787

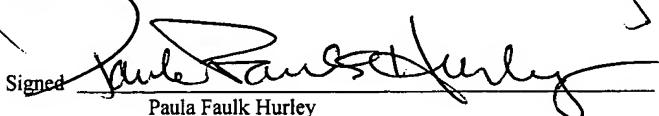
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

9-27-03
9-27-03
9-27-03

Applicant: R. PENDSE, *et al.*)
Application No.: 10/084,787)
Filed: February 25, 2002)
Title: Super-thin high speed flip chip package)
Examiner: Alexander O. WILLIAMS
Group Art Unit: 2826
Date: September 11, 2003
CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria VA 22313-1450, on September 11, 2003.

Signed 
Paula Faulk Hurley

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COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

REPLY TO OFFICE ACTION

Dear Sir:

Applicants respond as follows to the Office action, made final, mailed June 11, 2003:

There are no amendments to the claims. A **Listing of Claims** begins on page 2 of this paper.

Remarks begin on page 4 of this paper.

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